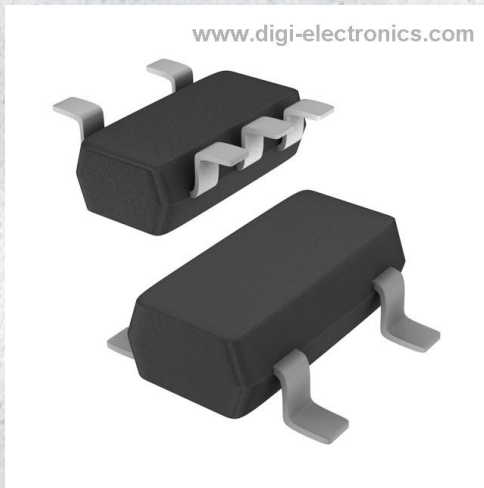


74AHC1G06GV,125 Datasheet



| | |
|------------------------------|---|
| DiGi Electronics Part Number | 74AHC1G06GV,125-DG |
| Manufacturer | NXP USA Inc. |
| Manufacturer Product Number | 74AHC1G06GV,125 |
| Description | IC INVERTER 1CH 1-INP 5TSOP |
| Detailed Description | Inverter IC 1 Channel Open Drain 5-TSOP |



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

74AHC1G06GV,125

Series:

74AHC

Logic Type:

Inverter

Number of Inputs:

1

Voltage - Supply:

2V ~ 5.5V

Current - Output High, Low:

-, 8mA

Input Logic Level - High:

1.5V ~ 3.85V

Operating Temperature:

-40°C ~ 125°C

Supplier Device Package:

5-TSOP

Base Product Number:

74AHC1G06

Manufacturer:

NXP USA Inc.

Product Status:

Obsolete

Number of Circuits:

1

Features:

Open Drain

Current - Quiescent (Max):

1 μ A

Input Logic Level - Low:

0.5V ~ 1.65V

Max Propagation Delay @ V, Max CL:

7ns @ 5V, 50pF

Mounting Type:

Surface Mount

Package / Case:

SC-74A, SOT-753

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

74AHC1G06; 74AHCT1G06

Inverter with open-drain output

Rev. 7 — 18 November 2014

Product data sheet

1. General description

74AHC1G06 and 74AHCT1G06 are high-speed Si-gate CMOS devices. They provide an inverting buffer. The output of these devices is an open-drain and can be connected to other open-drain outputs to implement active-LOW, wired-OR or active-HIGH, wired-AND functions. For digital operation this device must have a pull-up resistor to establish a logic HIGH-level.

The AHC device has CMOS input switching levels and supply voltage range 2 V to 5.5 V.

The AHCT device has TTL input switching levels and supply voltage range 4.5 V to 5.5 V.

2. Features and benefits

- High noise immunity
- Low power dissipation
- SOT353-1 and SOT753 package options
- ESD protection:
 - ◆ HBM JESD22-A114E: exceeds 2000 V
 - ◆ MM JESD22-A115-A: exceeds 200 V
 - ◆ CDM JESD22-C101C: exceeds 1000 V
- Specified from -40 °C to +125 °C

3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|--------------|-------------------|--------|--|----------|
| | Temperature range | Name | Description | Version |
| 74AHC1G06GW | -40 °C to +125 °C | TSSOP5 | plastic thin shrink small outline package; 5 leads; body width 1.25 mm | SOT353-1 |
| 74AHCT1G06GW | | | | |
| 74AHC1G06GV | -40 °C to +125 °C | SC-74A | plastic surface-mounted package; 5 leads | SOT753 |
| 74AHCT1G06GV | | | | |



4. Marking

Table 2. Marking codes

| Type number | Marking ^[1] |
|--------------|------------------------|
| 74AHC1G06GW | AR |
| 74AHC1G06GV | A06 |
| 74AHCT1G06GW | CR |
| 74AHCT1G06GV | C06 |

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

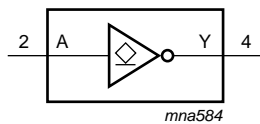


Fig 1. Logic symbol

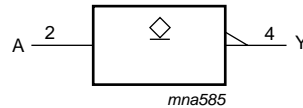


Fig 2. IEC logic symbol

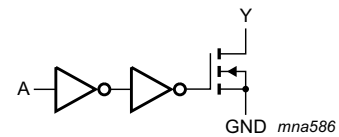


Fig 3. Logic diagram

6. Pinning information

6.1 Pinning

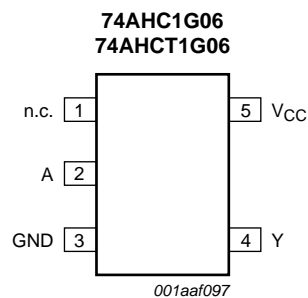


Fig 4. Pin configuration

6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|-----------------|-----|----------------|
| n.c. | 1 | not connected |
| A | 2 | data input |
| GND | 3 | ground (0 V) |
| Y | 4 | data output |
| V _{CC} | 5 | supply voltage |

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level; Z = high-impedance OFF-state

| Input | Output |
|-------|--------|
| A | Y |
| L | Z |
| H | L |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|-------------------------------|------|------|------|
| V_{CC} | supply voltage | | -0.5 | +7.0 | V |
| V_I | input voltage | | -0.5 | +7.0 | V |
| I_{IK} | input clamping current | $V_I < -0.5$ V | -20 | - | mA |
| I_{OK} | output clamping current | $V_O < -0.5$ V | [1] | ±20 | mA |
| I_O | output current | $V_O > -0.5$ V | - | ±25 | mA |
| V_O | output voltage | active mode | [1] | +7.0 | V |
| | | high-impedance mode | [1] | +7.0 | V |
| I_{CC} | supply current | | - | 75 | mA |
| I_{GND} | ground current | | -75 | - | mA |
| T_{stg} | storage temperature | | -65 | +150 | °C |
| P_{tot} | total power dissipation | $T_{amb} = -40$ °C to +125 °C | [2] | 250 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For both TSSOP5 and SC-74A packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 74AHC1G06 | | | 74AHCT1G06 | | | Unit |
|---------------------|-------------------------------------|--------------------------|-----------|-----|----------|------------|-----|----------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V_{CC} | supply voltage | | 2.0 | 5.0 | 5.5 | 4.5 | 5.0 | 5.5 | V |
| V_I | input voltage | | 0 | - | 5.5 | 0 | - | 5.5 | V |
| V_O | output voltage | active mode | 0 | - | V_{CC} | 0 | - | V_{CC} | V |
| | | high-impedance mode | 0 | - | 6.0 | 0 | - | 6.0 | V |
| T_{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |
| $\Delta t/\Delta V$ | input transition rise and fall rate | $V_{CC} = 3.3$ V ± 0.3 V | - | - | 100 | - | - | - | ns/V |
| | | $V_{CC} = 5.0$ V ± 0.5 V | - | - | 20 | - | - | 20 | ns/V |

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|--|---------------------------|--|-------|-----|-------|------------------|------|-------------------|-------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| For type 74AHC1G06 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | - | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 3.0 V | 2.1 | - | - | 2.1 | - | 2.1 | - | V |
| | | V _{CC} = 5.5 V | 3.85 | - | - | 3.85 | - | 3.85 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | - | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 3.0 V | - | - | 0.9 | - | 0.9 | - | 0.9 | V |
| | | V _{CC} = 5.5 V | - | - | 1.65 | - | 1.65 | - | 1.65 | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 50 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 3.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 3.0 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _O = 8.0 mA; V _{CC} = 4.5 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V | | |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | μA |
| I _{OZ} | OFF-state output current | V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; V _{CC} = 5.5 V | - | - | ±0.25 | - | ±2.5 | - | ±10.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.0 | - | 10 | - | 20 | μA |
| C _I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |
| For type 74AHCT1G06 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2.0 | - | - | 2.0 | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 4.5 V to 5.5 V | - | - | 0.8 | - | 0.8 | - | 0.8 | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 50 μA | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 8.0 mA | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | μA |
| I _{OZ} | OFF-state output current | V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; V _{CC} = 5.5 V | - | - | ±0.25 | - | ±2.5 | - | ±10.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.0 | - | 10 | - | 20 | μA |
| ΔI _{CC} | additional supply current | per input pin; V _I = 3.4 V; other inputs at V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.35 | - | 1.5 | - | 1.5 | mA |
| C _I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |

11. Dynamic characteristics

Table 8. Dynamic characteristics
GND = 0 V; $t_r = t_f = \leq 3.0$ ns. For test circuit see [Figure 6](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|----------------------------|------------------------------------|--|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| For type 74AHC1G06 | | | | | | | | | | |
| t _{PZL} | OFF-state to LOW propagation delay | A to Y; see Figure 5 | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V [1] | | | | | | | | |
| | | C _L = 15 pF | - | 3.7 | 7.0 | 1.0 | 7.7 | 1.0 | 8.1 | ns |
| | | C _L = 50 pF | - | 5.2 | 10.0 | 1.0 | 11.0 | 1.0 | 11.5 | ns |
| | | V _{CC} = 4.5 V to 5.5 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 2.7 | 4.9 | 1.0 | 5.3 | 1.0 | 5.6 | ns |
| | | C _L = 50 pF | - | 3.8 | 7.0 | 1.0 | 7.5 | 1.0 | 8.0 | ns |
| t _{PLZ} | LOW to OFF-state propagation delay | A to Y; see Figure 5 | | | | | | | | |
| | | V _{CC} = 3.0 V to 3.6 V [1] | | | | | | | | |
| | | C _L = 15 pF | - | 4.8 | 6.4 | 1.0 | 6.9 | 1.0 | 7.4 | ns |
| | | C _L = 50 pF | - | 6.9 | 10.0 | 1.0 | 10.5 | 1.0 | 11.0 | ns |
| | | V _{CC} = 4.5 V to 5.5 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 3.0 | 4.1 | 1.0 | 4.6 | 1.0 | 5.1 | ns |
| | | C _L = 50 pF | - | 4.3 | 6.5 | 1.0 | 7.0 | 1.0 | 7.5 | ns |
| C _{PD} | power dissipation capacitance | per buffer; C _L = 50 pF; f = 1 MHz; V _I = GND to V _{CC} [3] | - | 3 | - | - | - | - | - | pF |
| For type 74AHCT1G06 | | | | | | | | | | |
| t _{PZL} | OFF-state to LOW propagation delay | A to Y; see Figure 5 | | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 3.0 | 5.3 | 1.0 | 6.0 | 1.0 | 6.3 | ns |
| | | C _L = 50 pF | - | 4.2 | 7.5 | 1.0 | 8.5 | 1.0 | 9.0 | ns |
| t _{PLZ} | LOW to OFF-state propagation delay | A to Y; see Figure 5 | | | | | | | | |
| | | V _{CC} = 4.5 V to 5.5 V [2] | | | | | | | | |
| | | C _L = 15 pF | - | 3.2 | 4.6 | 1.0 | 5.1 | 1.0 | 5.6 | ns |
| | | C _L = 50 pF | - | 4.5 | 7.0 | 1.0 | 7.5 | 1.0 | 8.0 | ns |
| C _{PD} | power dissipation capacitance | per buffer; C _L = 50 pF; f = 1 MHz; V _I = GND to V _{CC} [3] | - | 4.5 | - | - | - | - | - | pF |

[1] Typical values are measured at V_{CC} = 3.3 V.

[2] Typical values are measured at V_{CC} = 5.0 V.

[3] C_{PD} is used to determine the dynamic power dissipation P_D (μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

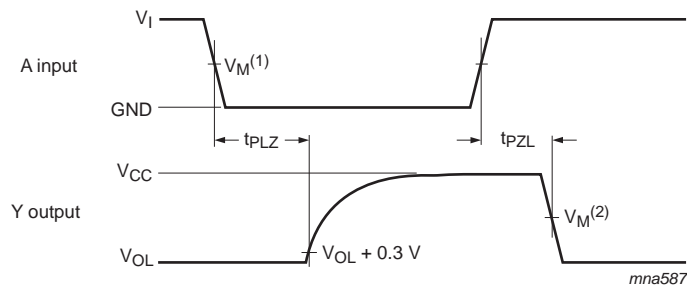
f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts

12. Waveforms

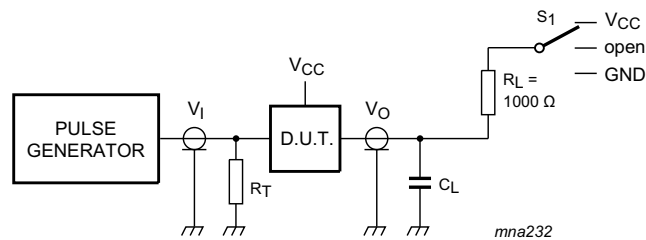


Measurement points are given in [Table 9](#).

Fig 5. Input (A) to output (Y) propagation delays

Table 9. Measurement point

| Type | Input | | Output |
|------------|-----------------|---------------------|---------------------|
| | V_I | $V_M^{(1)}$ | $V_M^{(2)}$ |
| 74AHC1G06 | GND to V_{CC} | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ |
| 74AHCT1G06 | GND to 3.0 V | 1.5 V | $0.5 \times V_{CC}$ |



Test data is given in [Table 8](#). Definitions for test circuit:

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

For t_{PLZ} , t_{PZL} , $S_1 = V_{CC}$

Fig 6. Test circuit for measuring switching times

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1

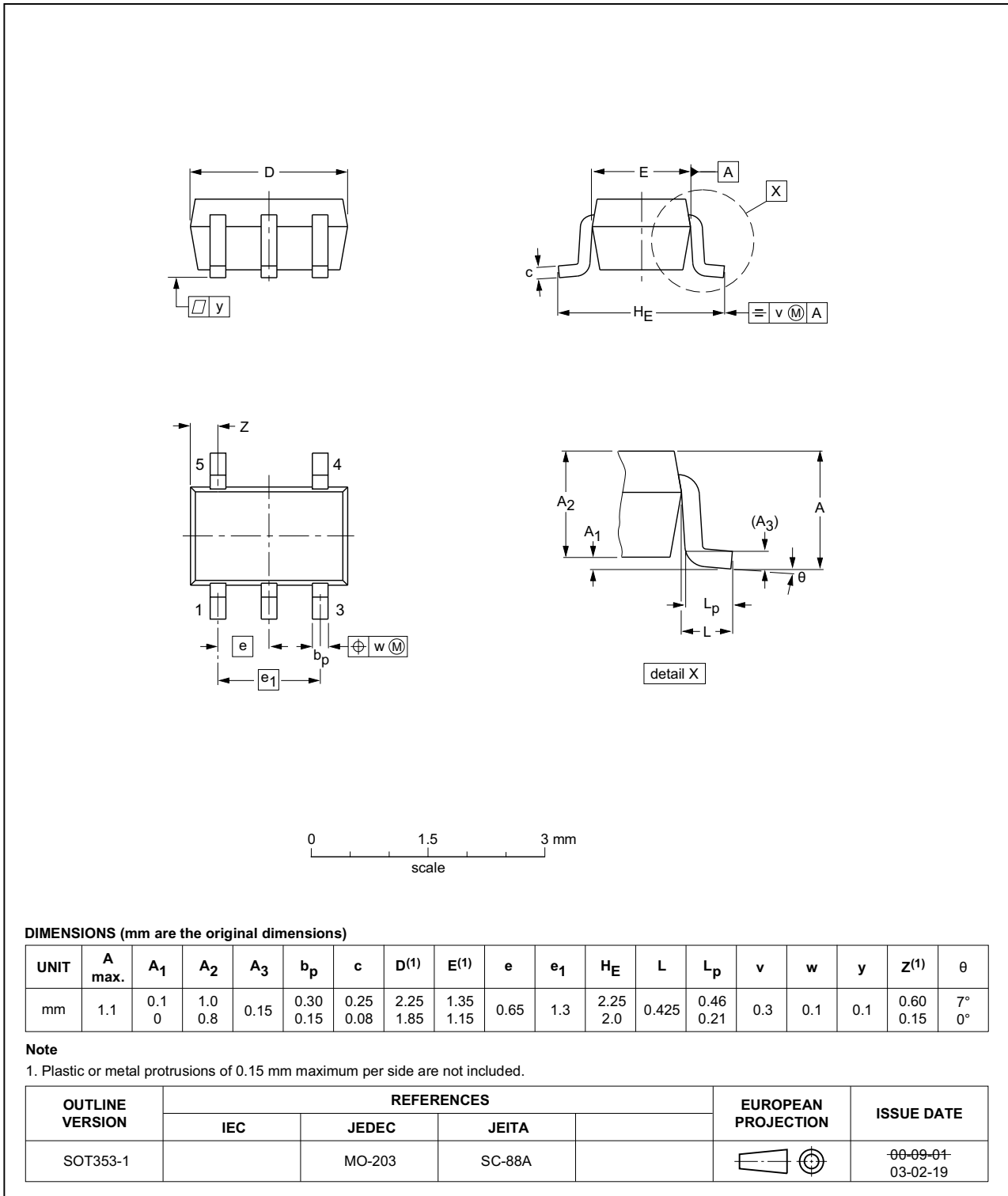


Fig 7. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

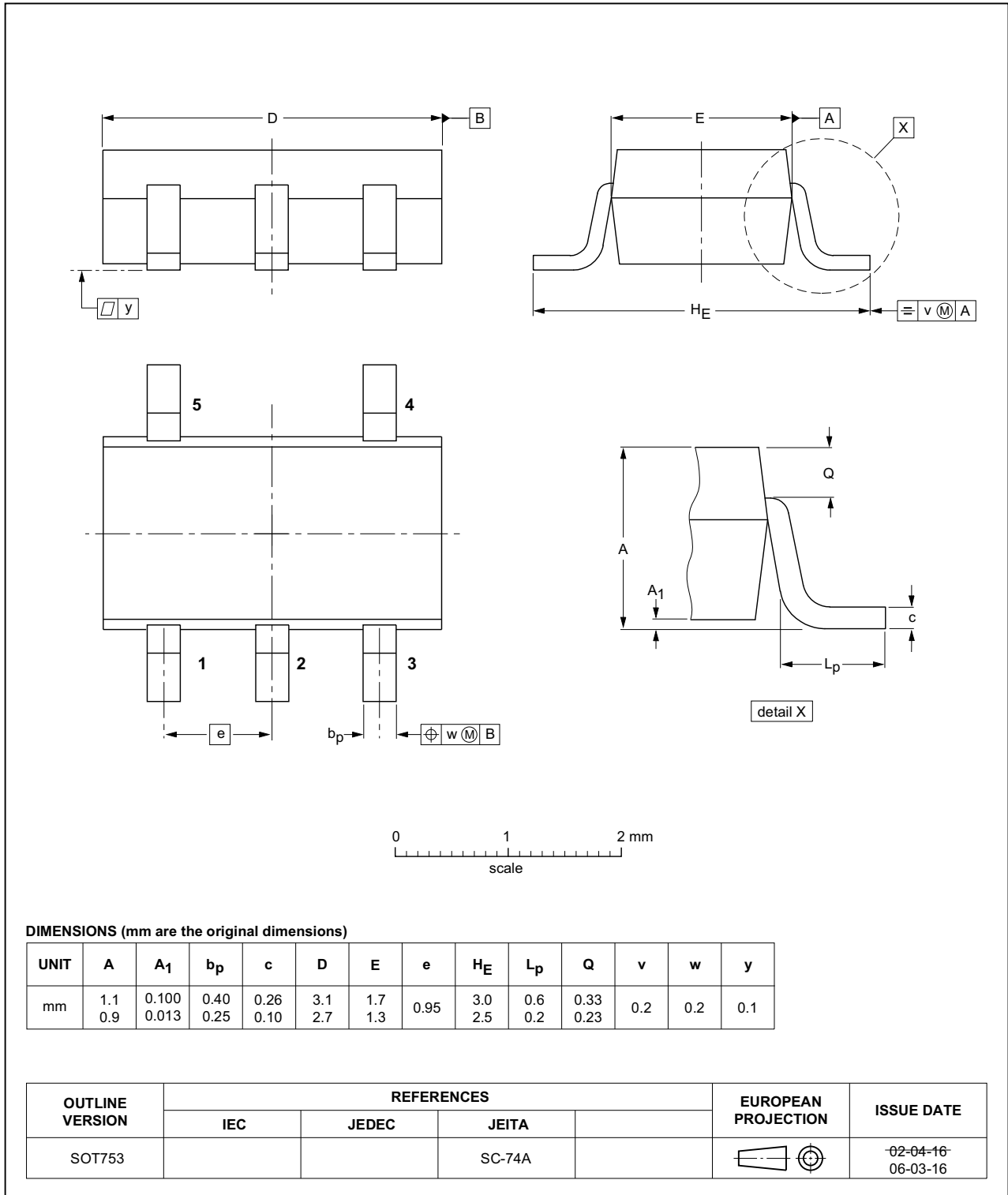


Fig 8. Package outline SOT753 (SC-74A)

14. Abbreviations

Table 10. Abbreviations

| Acronym | Description |
|---------|-----------------------------|
| CDM | Charged Device Model |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

15. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|--------------------|--|-----------------------|---------------|--------------------|
| 74AHC_AHCT1G06 v.7 | 20141118 | Product data sheet | - | 74AHC_AHCT1G06 v.6 |
| Modifications: | <ul style="list-style-type: none"> • Section 4: table note added. | | | |
| 74AHC_AHCT1G06 v.6 | 20070607 | Product data sheet | - | 74AHC_AHCT1G06 v.5 |
| Modifications: | <ul style="list-style-type: none"> • The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Package SOT353 changed to SOT353-1 in Section 3 and Section 13. • Quick reference data and Soldering sections removed. | | | |
| 74AHC_AHCT1G06 v.5 | 20021002 | Product specification | - | 74AHC_AHCT1G06 v.4 |
| 74AHC_AHCT1G06 v.4 | 20020528 | Product specification | - | 74AHC_AHCT1G06 v.3 |
| 74AHC_AHCT1G06 v.3 | 20020221 | Product specification | - | 74AHC_AHCT1G06 v.2 |
| 74AHC_AHCT1G06 v.2 | 20010209 | Product specification | - | 74AHC_AHCT1G06 v.1 |
| 74AHC_AHCT1G06 v.1 | 20000501 | Product specification | - | - |

16. Legal information

16.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

16.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

Product specification — The information and data provided in a Product data sheet shall define the specification of the product as agreed between NXP Semiconductors and its customer, unless NXP Semiconductors and customer have explicitly agreed otherwise in writing. In no event however, shall an agreement be valid in which the NXP Semiconductors product is deemed to offer functions and qualities beyond those described in the Product data sheet.

16.3 Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products.

NXP Semiconductors does not accept any liability related to any default, damage, costs or problem which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors hereby expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b) whenever customer uses the product for automotive applications beyond

NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

Translations — A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

17. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

18. Contents

| | | |
|-----------|---|-----------|
| 1 | General description | 1 |
| 2 | Features and benefits | 1 |
| 3 | Ordering information | 1 |
| 4 | Marking | 2 |
| 5 | Functional diagram | 2 |
| 6 | Pinning information | 2 |
| 6.1 | Pinning | 2 |
| 6.2 | Pin description | 2 |
| 7 | Functional description | 3 |
| 8 | Limiting values | 3 |
| 9 | Recommended operating conditions | 3 |
| 10 | Static characteristics | 4 |
| 11 | Dynamic characteristics | 5 |
| 12 | Waveforms | 6 |
| 13 | Package outline | 7 |
| 14 | Abbreviations | 9 |
| 15 | Revision history | 9 |
| 16 | Legal information | 10 |
| 16.1 | Data sheet status | 10 |
| 16.2 | Definitions | 10 |
| 16.3 | Disclaimers | 10 |
| 16.4 | Trademarks | 11 |
| 17 | Contact information | 11 |
| 18 | Contents | 12 |

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP Semiconductors N.V. 2014.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 18 November 2014

Document identifier: 74AHC_AHCT1G06

OUR CERTIFICATE

DiGi provide top-quality products and perfect service for customer worldwide through standardization, technological innovation and continuous improvement. DiGi through third-party certification, we stricly control the quality of products and services. Welcome your RFQ to

Email: Info@DiGi-Electronics.com



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.